TIG®780-20
Thermal Grease

TIG®780-20 is a paste like thermal interface material designed specifically for the heat dissipation of various low and medium power electronic components. Under typical assembly pressure and small filling thickness, the material can fully wet the contact surface, effectively eliminate interface air, and form a continuous heat conduction path. This product can be widely used in general electronic equipment cooling scenarios that require both cost and performance, such as network communication, security monitoring, household appliances, and conventional industrial control hardware.



Features

》Low viscosity

》Good thermal conductivity

》Excellent wettability, capable of fully infiltrating and contacting the surface

》Non-toxic and environmentally friendly

Applications

》LED lighting

》ASICS chip

》Interface filling of CPU, GPU, and heat dissipation module

》Vehicle control unit

Typical Properties of TIG®780-20

Property	Value	Test Method
Color	White	Visual
Construction	Ceramic filled silicone	-
Bond Line Thickness (mm)	0.036	-
Density (g/cm^3)	2.8	ASTM D792
Viscosity (mPa·s) @25℃	130000	GB/T 10247
Recommended Operating Temperature (°C)	-45~200	-
Breakdown Strength (V/mm)	≥6000	ASTM D149
Thermal Impedance (℃·in^2/W) @30psi	0.047	ASTM D5470
Thermal Conductivity (W/m·K)	2.0	ASTM D5470
	2.0	ISO22007

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